## SUPPLEMENTAL INFORMATION

## 1. Flux calculations

The Ga and In beam equivalent pressures are converted into particle fluxes  $\Phi_{Me}$  (cm<sup>-2</sup>s<sup>-1</sup>) in Fig. 4b-d according to kinetic gas theory:<sup>58</sup>

$$\Phi_{Me}^{BEP} = C \frac{\rho_{Me}}{\sqrt{2\pi m_{Me} k_B T}},$$

$$\Phi_{Me} = I_{Me} \Phi_{Me}^{BEP},$$
(10)

Where  $m_{Me}$  is the atomic mass, T is the effusion cell temperature, C = 0.013332 cm<sup>-2</sup>s<sup>-1</sup> is a prefactor to convert  $\Phi_{Me}^{BEP}$  from torr to particle flux, and  $I_{Me}$  is an effective factor determined from metal-limited sensitivity calibration growth. The Ga sensitivity factor  $I_{Ga}$  was determined from homoepitaxial growth of Ga<sub>2</sub>O<sub>3</sub> with a typical growth rate of 3.16 nm/min, and the In sensitivity factor  $I_{In}$  was estimated as  $I_{In} = I_{Ga}(5.2/9.1)$  in accordance with the experimentally obtained factors reported in Ref. 60. The oxygen beam equivalent pressure  $\Phi_{0}^{BEP} = 3.2 \times 10^{15} \text{ cm}^{-2} \text{s}^{-1} \text{ at } 3.00 \text{ SCCM and } 250 \text{ W was}$ calculated from the growth rate of slightly metal-rich homoepitaxial Ga<sub>2</sub>O<sub>3</sub> growth at 650 °C. The effective oxygen flux  $\Phi^{*,Me}_{0}$  available for Ga<sub>2</sub>O<sub>3</sub> and In<sub>2</sub>O<sub>3</sub> growth varies for each metal species due to the differing oxidation efficiencies<sup>34,54,58</sup> and is given by:

$$\Phi^{*,Me}_{\ 0} = J^{Me}_{\ 0} \Phi^{BEP}_{\ 0}.$$
 (11)

In the presence of both Ga and In flux, the total effective oxygen flux  $\Phi_0^*$  is modified by the metal flux ratio  $R = \Phi_{In}/(\Phi_{Ga} + \Phi_{In})$ . with<sup>58</sup>

$$\Phi_0^* = \Phi_0^{BEP} \left( R J_0^{ln} + (1 - R) J_0^{Ga} \right).$$
(12)

The total metal/oxygen flux ratio is thus  $(\Phi_{Ga} + \Phi_{In})/\Phi_0^*$ and the stoichiometric flux ratio shown in Fig. 4d is  $\frac{3}{2}(\Phi_{Ga} + \Phi_{In})/\Phi_0^*$  The flux calibration parameters are

 $\overline{2}^{(\Phi_{Ga} + \Phi_{In})/\Phi_{O}}$ . The flux calibration parameters are summarized in Table I.

TABLE I. Flux calibration parameters for Ga and In.

Metal	Ga	In
Atomic mass, $m_{Me}$ (amu)	69.723	114.818
Sensitivity factor, $I_{Me}$	10.60	6.06
Oxidation efficiency, $J_0^{Me}$	0.096	0.263

## 2. X-ray diffraction of phase separated growth

Fig. 7 shows a coupled  $\omega$ -2 $\theta$  x-ray diffraction scan for a targeted growth performed at 740 °C with relatively high In and Ga fluxes of 3×10-7 torr each. The dashed lines indicate the locations of the  $\beta$ -Ga<sub>2</sub>O<sub>3</sub> (020) reflection at  $\omega$ = 30.481° and the bixbyite In<sub>2</sub>O<sub>3</sub> (444) reflection at  $\omega$  =  $31.824^{\circ}$ . The presence of the measured bixbyite In<sub>2</sub>O<sub>3</sub> (444) peak reflects the terminal RHEED pattern which developed into a spotty/faceted pattern typical of Fig. 3b, confirming that this pattern is due to the formation of  $In_2O_3$ on the surface. No compressive features are observed at diffraction angles below the  $\beta$ -Ga<sub>2</sub>O<sub>3</sub> (020) peak, confirming that In does not incorporate at these high metal flux growth conditions. RBS measurements for this sample (not shown) confirm the presence of a thin In-rich layer at the surface. Reaction equations (4) through (8) suggest that In<sub>2</sub>O<sub>3</sub> formation is suppressed at these metal rich conditions due to a combination of In<sub>2</sub>O formation and Ga cation exchange followed by Ga<sub>2</sub>O decomposition. The presence of a thin In<sub>2</sub>O<sub>3</sub> layer suggests that complete decomposition of In<sub>2</sub>O<sub>3</sub> does not occur. The accumulation of In<sub>2</sub>O<sub>3</sub> is very small, however, on the order of several nanometers over the course of a 1 hour growth.



FIG. 7. Coupled  $\omega$ -2 $\theta$  x-ray diffraction (XRD) scan of targeted growth with spotty/faceted surface reconstruction. Growth conditions labeled directly on figure. The peak at  $\omega = 31.824^{\circ}$  is attributed to the (444) reflection from bixbyite In<sub>2</sub>O<sub>3</sub>, responsible for the spotty/faceted RHEED pattern.

## 3. Orientation of bixbyite $In_2O_3$ on (010) $\beta$ -Ga<sub>2</sub>O<sub>3</sub>

Fig. 8 shows the possible orientation of bixbyite  $In_2O_3$ on (010) oriented  $\beta$ -Ga<sub>2</sub>O<sub>3</sub>. The  $In_2O_3$  [111] direction is parallel to the Ga<sub>2</sub>O<sub>3</sub> [010] direction and is perpendicular to the growth plane of the substrate. The  $In_2O_3$  [011] direction is perpendicular to the Ga<sub>2</sub>O<sub>3</sub> [001] direction. This orientation is responsible for the bixbyite  $In_2O_3$  (444) peak observed in the coupled  $\omega$ -20 XRD scan shown in Fig. 7 for the phase separated growth, and for the ~7.1 Å spot spacing observed in the RHEED pattern shown in Fig. 3b corresponding to diffraction from the  $In_2O_3$  (110) plane.



FIG. 8. Possible orientation of bixbyite  $In_2O_3$  on (010) oriented  $\beta$ -Ga<sub>2</sub>O<sub>3</sub>.